

AN-1685 LM3405A Demo Board

1 Introduction

The LM3405A demo board is configured to drive a series string of high power, high brightness LEDs at a forward current of 1A using the LM3405A constant current buck regulator. The board can accept a full input operating range of 3V to 22V. The converter output voltage adjusts as needed to maintain a constant current through the LED array. The LM3405A is a step-down regulator with an output voltage range extending from a $V_{O(MIN)}$ of 205 mV (the reference voltage) to a $V_{O(MAX)}$ determined by the maximum duty cycle (typically 94%). It can drive up to 5 LEDs in series at 1A forward current, with the single LED forward voltage of approximately 3.7 V (typical of white, blue, and green LEDs using InGaN technology).

As shown in the demo board schematic circuit in [Figure 1](#), the board is configured with the boost voltage derived from V_{IN} through a shunt zener (D3). This will ensure that the gate drive voltage $V_{BOOST} - V_{SW}$ falls in the recommended range of 2.5 V to 5.5 V when V_{IN} varies from 5 V to 22 V. When input voltage is in the range of 3 V to 5 V, the anode of boost diode (D2) should be directly connected to V_{IN} by replacing R3 with a jumper and removing C4 and D3, to obtain sufficient gate drive voltage for best performance.

[Table 1](#) lists the bill of materials (BOM) of this demo board. The measured performance characteristics and layout of this board are also included below. Additionally, the *Circuit Configuration Schematics* section illustrates other possible circuit configurations of this board to accommodate various input and output requirements as discussed in the *LM3405A 1.6MHz, 1A Constant Current Buck LED Driver with Internal Compensation in Tiny SOT and MSOP PowerPAD Packages Data Sheet* ([SNVS508](#)).

2 Connecting to LED Array

The LM3405A demo board includes a female 6-position SIP connector **P1** as well as two standard 72mil turret connectors for the cathode and anode connections of the LED array. Solid 18 or 20 gauge wire with about 1cm of insulation stripped away makes a convenient, solderless connection to **P1**.

3 Setting the LED Current

The default forward current I_F delivered to the LED array is 1.0A. To adjust this value the current setting resistor R1 can be changed according to [Equation 1](#):

$$I_F = V_{FB} / R1 \tag{1}$$

The feedback voltage V_{FB} is typically regulated at 0.205 V. The resistor R1 should be rated to handle the power dissipation of the LED current. R1 should be less than approximately 1 Ω , to ensure that the LED current is kept above 200 mA. If average LED currents of less than 200 mA are desired, the EN/DIM pin should be used for pulse width modulation (PWM) dimming.

4 PWM Dimming

The default connection of the PWM terminal is tied to V_{IN} through a 100 k Ω resistor (R2) to enable the chip, which allows the set current to flow through the LEDs continuously. This PWM terminal can also be connected to a periodic pulse signal at different frequencies and/or duty cycle for PWM dimming. A typical LED current waveform in PWM dimming mode is shown in [Figure 2](#). [Figure 3](#) shows the average LED current versus duty cycle of various dimming signal frequencies. Due to an approximately 100 μ s delay between the dimming signal and LED current, the dimming ratio reduces dramatically if the applied PWM dimming frequency is greater than 5 kHz.

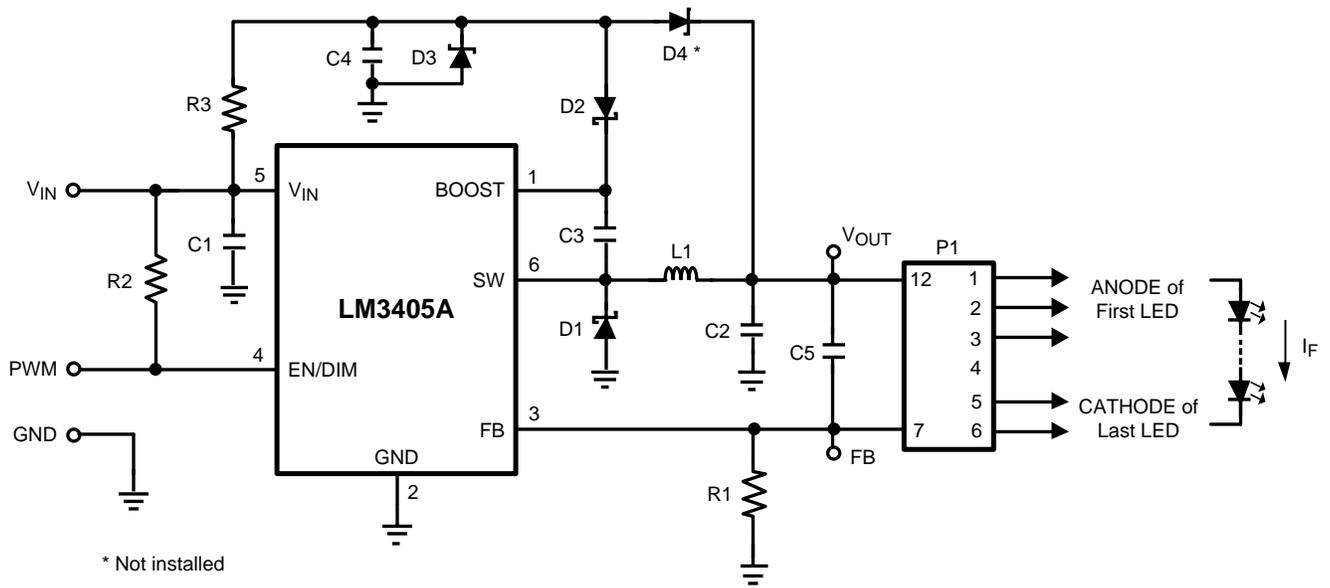


Figure 1. LM3405A Demo Board Schematic

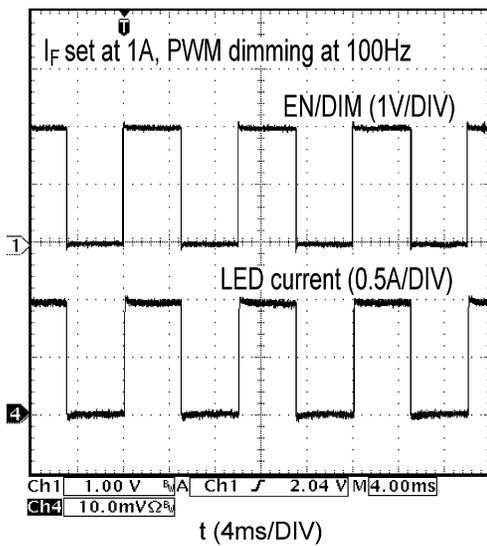


Figure 2. PWM Dimming of LEDs

Figure .

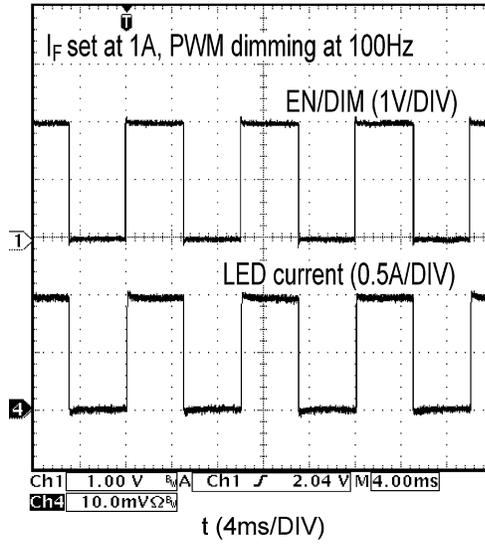


Figure 3. Average LED Current versus Duty Cycle of PWM Dimming Signal at PWM Terminal

5 Bill of Materials (BOM)

Table 1. Bill of Materials (BOM)

Part ID	Part Value	Part Number	Manufacturer
U1	1A constant current buck regulator, SOT-6	LM3405A	Texas Instruments
L1	10 μ H, 1.3A, 53 m Ω , 6.0 x 6.0 x 2.8 mm	SLF6028T-100M1R3-PF	TDK
C1	10 μ F, 25 V, X5R, 1206	GRM31CR61E106KA12L	Murata
C2	1 μ F, 35 V, X7R, 1206	GMK316BJ105KL-T	Taiyo Yuden
C3	0.01 μ F, 16 V, X7R, 0805	0805YC103KAT2A	AVX
C4	0.1 μ F, 16 V, X7R, 0805	GRM219R71C104KA01D	Murata
C5	1 μ F, 35 V, X7R, 0805	GMK212BJ105KG-T	Taiyo Yuden
D1	Schottky, 40 V, 1A, SMA	SS14-E3/61T	Vishay
D2	Schottky, 30 V, 200 mA, SOD-323	BAT54WS-TP	Micro Commercial Co.
D3	5.1 V, 0.35W, SOT23	MMBZ5231B-7-F	Diodes
D4	Not installed		
R1	0.5W, 0.2 Ω , 1%, 2010	WSL2010R2000FEA	Vishay
R2	100 k Ω , 1/8W, 1%, 0805	CRCW0805100KFKEA	Vishay
R3	1.0 k Ω , 1%, 1/8W, 0805	CRCW08051K00FKEA	Vishay
P1	6-position connector	5535676-5	Tyco/AMP

6 Typical Performance Characteristics

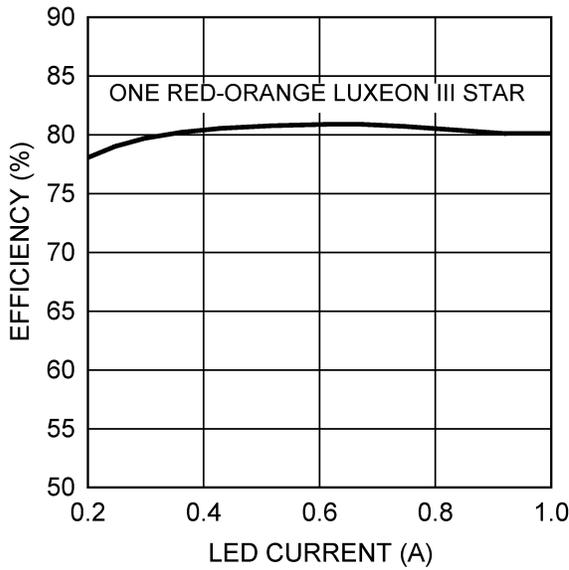


Figure 4. Efficiency vs LED Current (V_{IN} = 5 V, V_{BOOST} Derived from V_{IN})

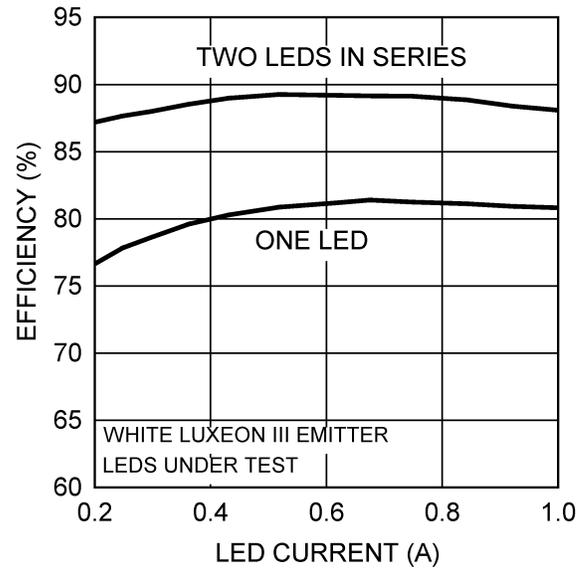


Figure 5. Efficiency vs LED Current (V_{IN} = 12 V)

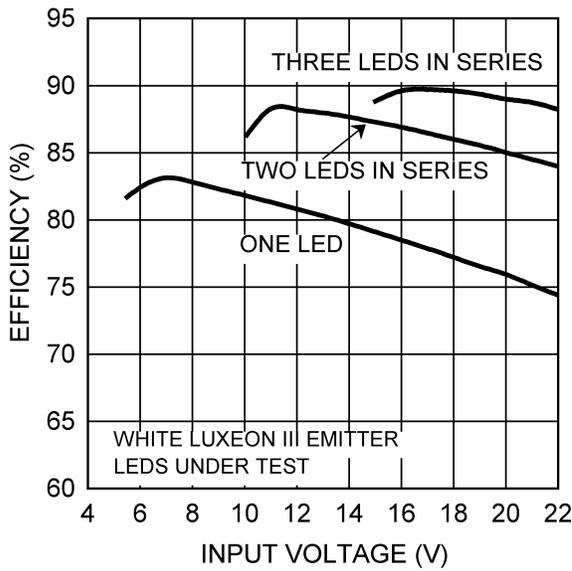


Figure 6. Efficiency vs Input Voltage (I_F = 1 A)

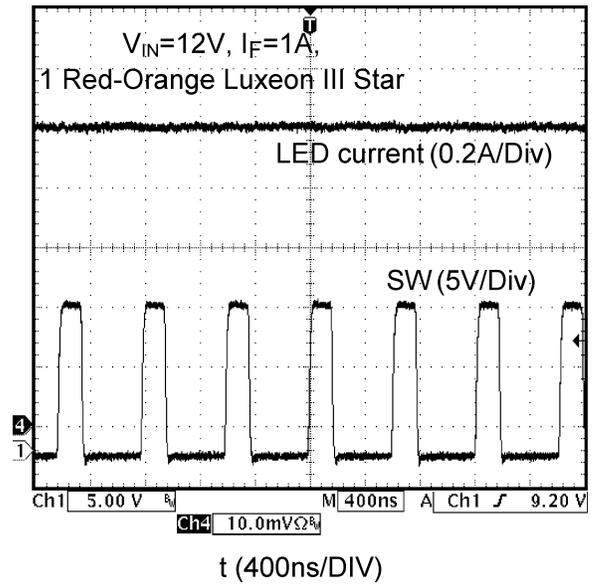
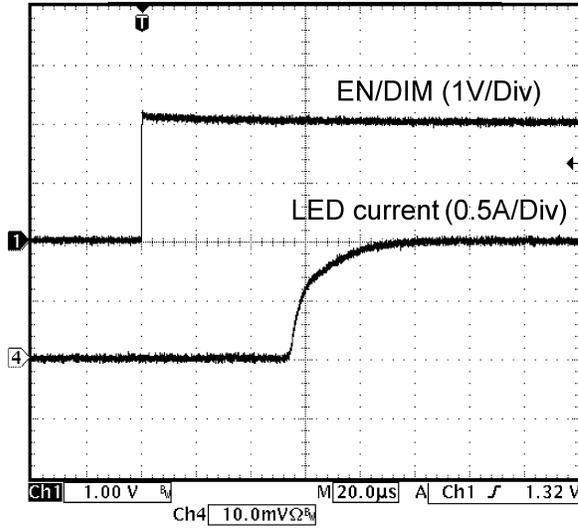
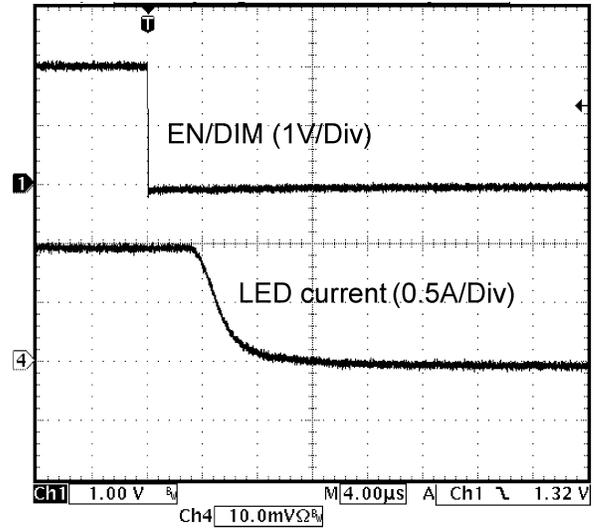


Figure 7. Switching Waveforms



t (20µs/DIV)

Figure 8. Startup During PWM Dimming
($V_{IN} = 12\text{ V}$, $I_F = 1\text{ A}$)



t (4µs/DIV)

Figure 9. Shutdown During PWM Dimming
($V_{IN} = 12\text{ V}$, $I_F = 1\text{ A}$)

7 Layout

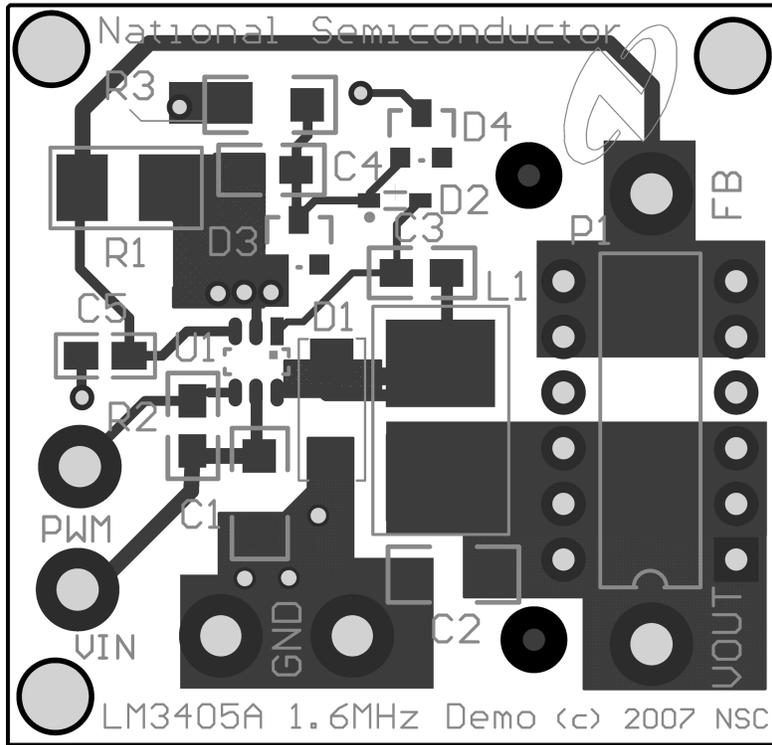


Figure 10. Top Layer and Top Overlay

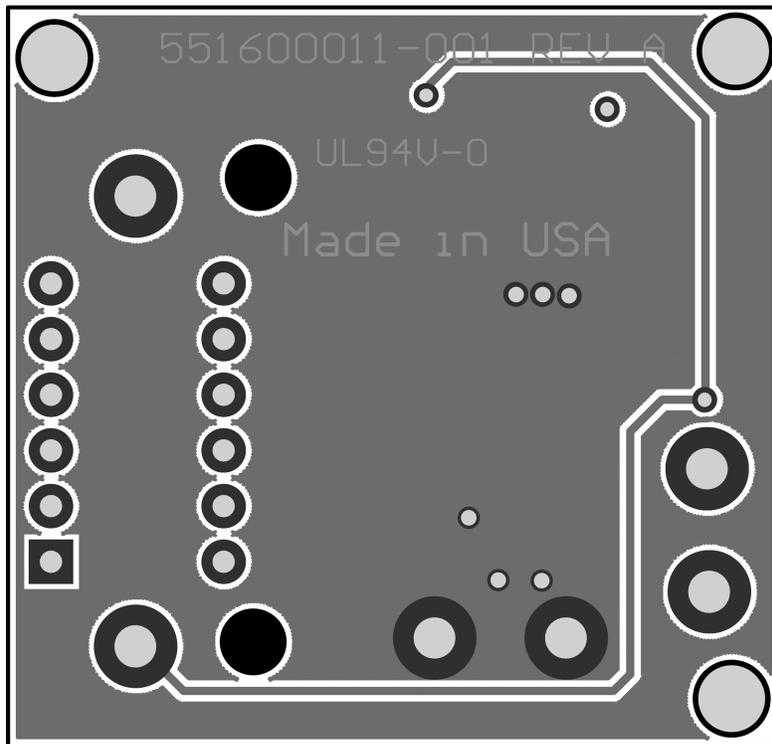


Figure 11. Bottom Layer and Bottom Overlay

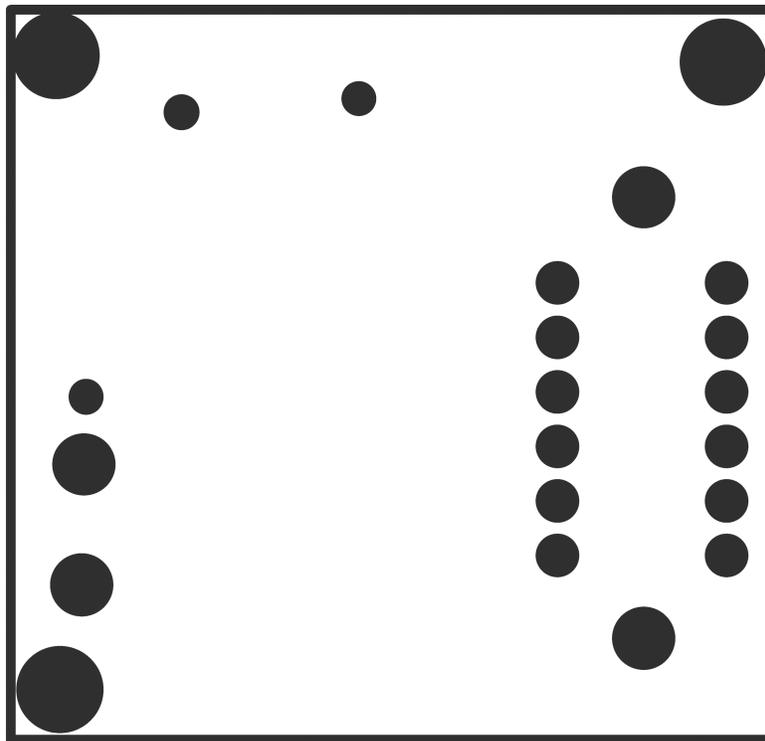


Figure 12. Internal Plane 1 (GND)

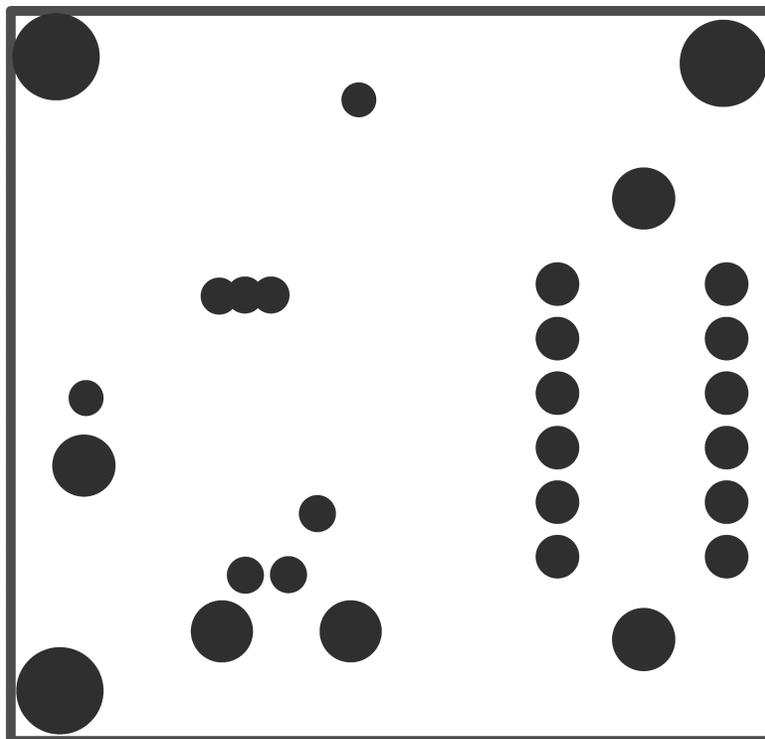


Figure 13. Internal Plane 2 (V_{IN})

8 Additional Circuit Configuration Schematics

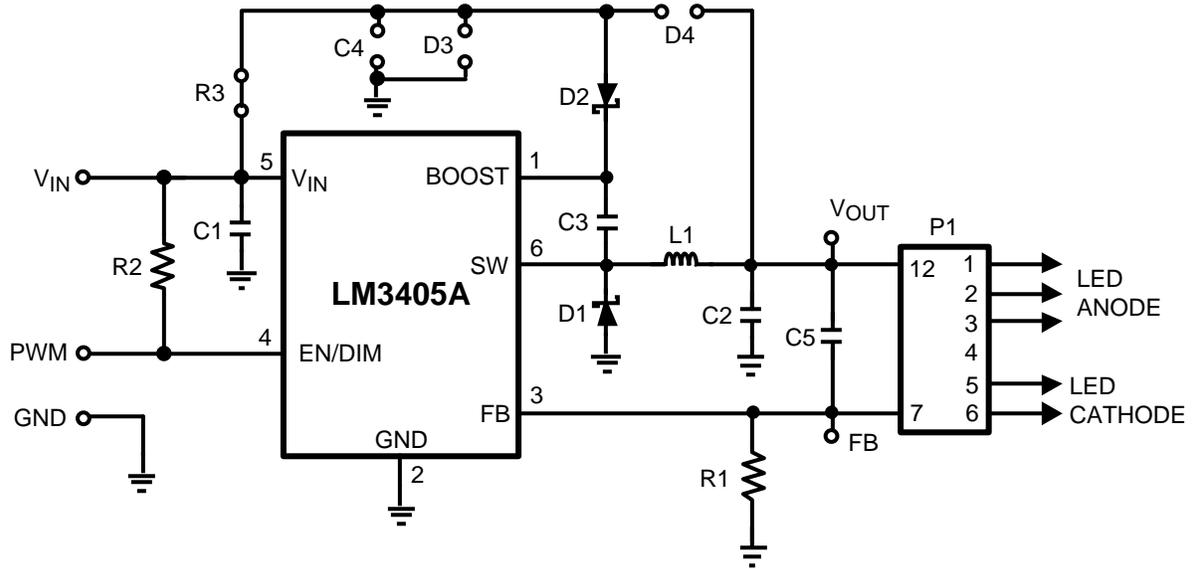


Figure 14. V_{BOOST} Derived from V_{IN}

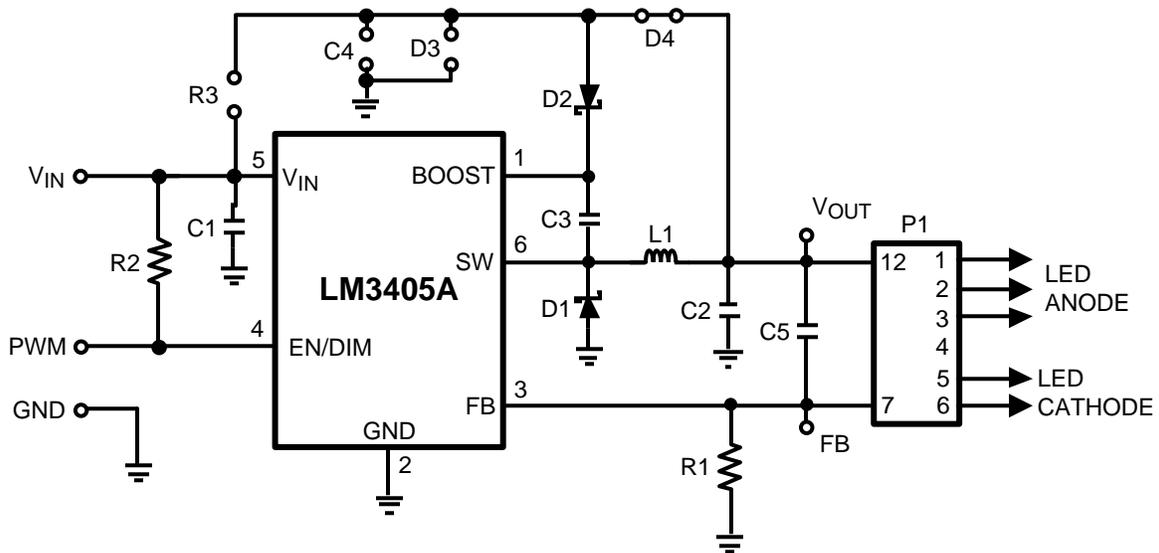


Figure 15. V_{BOOST} Derived from V_{OUT}

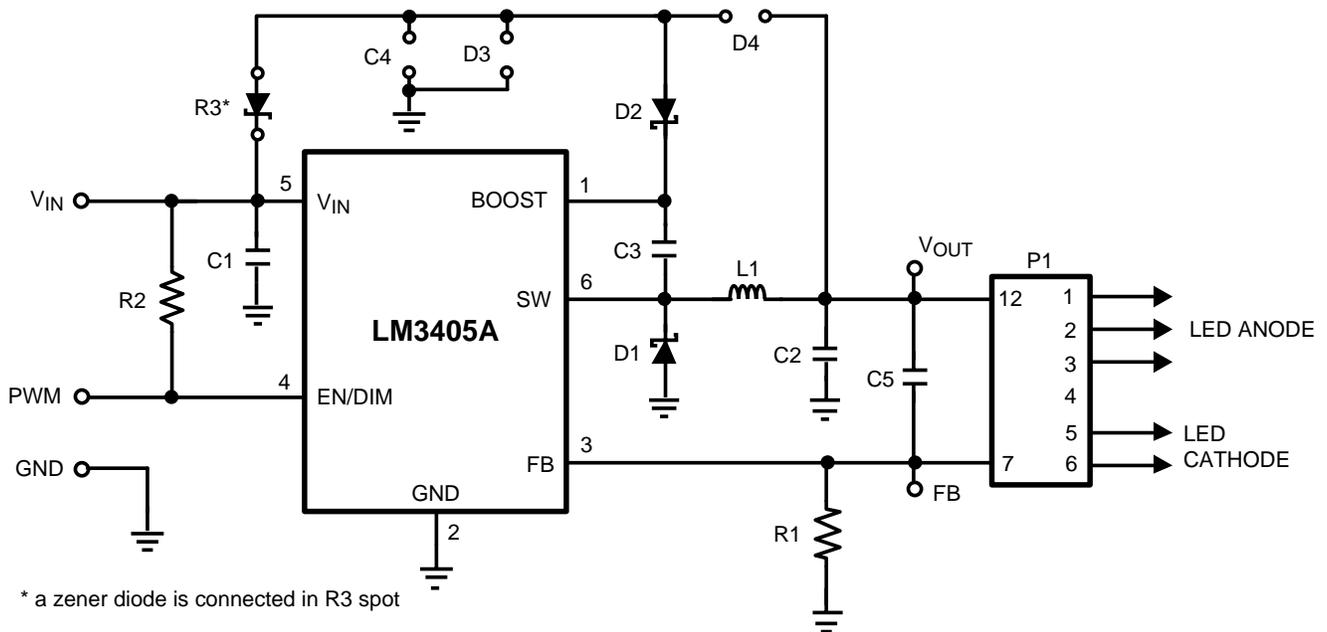


Figure 16. V_{BOOST} Derived from V_{IN} through a Series Zener Diode

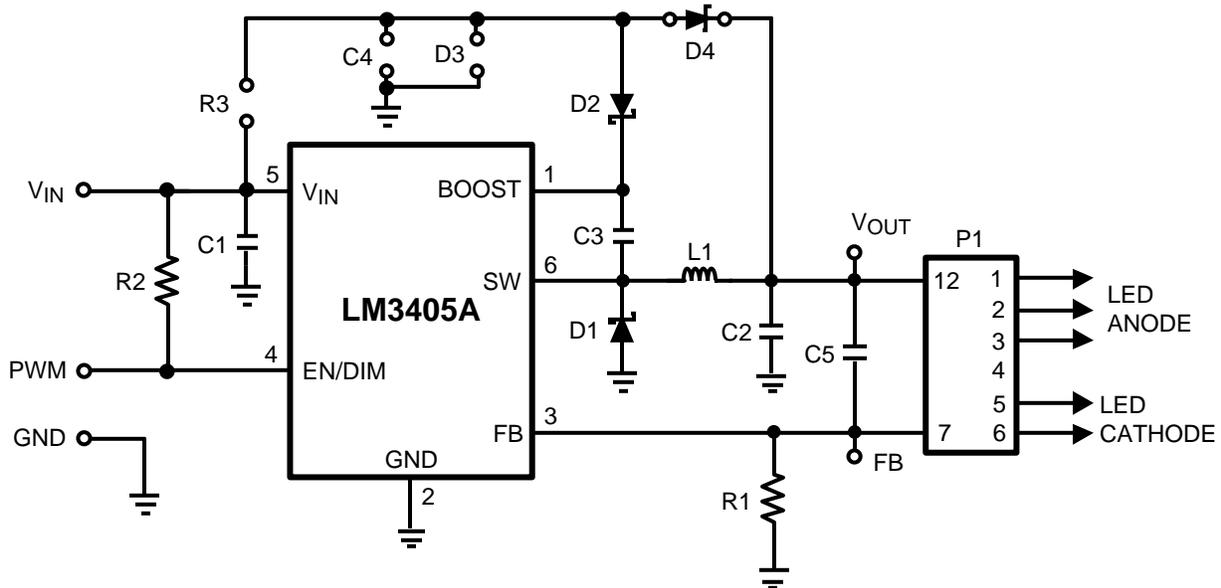


Figure 17. V_{BOOST} Derived from V_{OUT} through a Series Zener Diode

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com